505358616 03/05/2019

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5405404

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MICHAEL W. PACIER	02/22/2019
MICHAEL J. SERSHEN	02/22/2019
ADAM F. BERTUCH	02/27/2019
LAURENT LECORDIER	02/28/2019

RECEIVING PARTY DATA

Name:	VEECO INSTRUMENTS INC.	
Street Address:	1 TERMINAL DRIVE	
City:	PLAINVIEW	
State/Country:	NEW YORK	
Postal Code:	11803	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	29680874

CORRESPONDENCE DATA

Fax Number: (802)862-7512

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 802-863-2375

Email: patip@drm.com

Correspondent Name: KEVIN C. MCGRATH, ESQ.

Address Line 1: 199 MAIN STREET

Address Line 4: BURLINGTON, VERMONT 05401

ATTORNEY DOCKET NUMBER:	16702-075USX2	
NAME OF SUBMITTER:	KEVIN C. MCGRATH	
SIGNATURE:	/Kevin C. McGrath/	
DATE SIGNED:	03/05/2019	

Total Attachments: 4

source=20190222_PacierAssignment_075USX2#page1.tif source=20190222_SershenAssignment_075USX2#page1.tif source=20190227_BertuchAssignment_075USX2#page1.tif

PATENT 505358616 REEL: 048507 FRAME: 0236

 $source = 20190228_Lecordier Assignment_075 USX2\#page 1.t if$

PATENT REEL: 048507 FRAME: 0237

ASSIGNMENT.

Whereas, I, Michael W. Pacier, residing in Leominster, Massachusetts, have invented one or more new and useful inventions and have filed therefor United States Design Patent Application Serial No. 29/680,874, filed on February 20, 2019, entitled "Transportable Semiconductor Wafer Rack" (hereinafter, "Application(s)");

And whereas, And whereas, Veeco Instruments Inc., a Delaware corporation, having a place of business at 1 Terminal Drive, Plainview, New York 11803 (hereinafter called Assignee), desires to acquire the entire right, title and interest in the Application(s) and all inventions disclosed therein, and to any United States and foreign patents to be obtained therefor, and to any United States, international, and foreign patent applications to be filed thereon;

Now therefore, for good and valuable consideration, receipt whereof is hereby acknowledged, I, the above-named inventor hereby sell, assign, and transfer to Assignee, its successors and assigns, and confirm any previous assignments made by me for, the entire right, title and interest in the Application(s) and inventions therein disclosed for the United States and foreign countries, including all provisional applications relating thereto, all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents which may have been granted or may be granted hereafter thereon, and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon, and all rights of priority resulting from any of the foregoing.

And I hereby agree that Assignee may file one or more international applications and apply for foreign Letters Patent on said inventions; and I request the Commissioner for Patents of the United States Patent and Trademark Office and the authorized official in each respective foreign patent office to issue any Letters Patent granted upon the inventions set forth in the Application(s) to Assignee; and I will execute all papers necessary in connection with the United States, international, and foreign applications when called upon to do so by Assignee.

I, the above-named, hereby covenant that no assignment, sale, agreement, or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Executed at <u>UALTRAM</u> (city/town), Massachusetts, this <u>H</u>day of February, 2019.

Michael W. Packer

ASSIGNMENT

Whereas, I, **Michael J. Sershen**, residing in Cambridge, Massachusetts, have invented one or more new and useful inventions and have filed therefor United States Design Patent Application Serial No. 29/680,874, filed on February 20, 2019, entitled "Transportable Semiconductor Wafer Rack" (hereinafter, "Application(s)");

And whereas, And whereas, Veeco Instruments Inc., a Delaware corporation, having a place of business at 1 Terminal Drive, Plainview, New York 11803 (hereinafter called Assignee), desires to acquire the entire right, title and interest in the Application(s) and all inventions disclosed therein, and to any United States and foreign patents to be obtained therefor, and to any United States, international, and foreign patent applications to be filed thereon;

Now therefore, for good and valuable consideration, receipt whereof is hereby acknowledged, I, the above-named inventor hereby sell, assign, and transfer to Assignee, its successors and assigns, and confirm any previous assignments made by me for, the entire right, title and interest in the Application(s) and inventions therein disclosed for the United States and foreign countries, including all provisional applications relating thereto, all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents which may have been granted or may be granted hereafter thereon, and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon, and all rights of priority resulting from any of the foregoing.

And I hereby agree that Assignee may file one or more international applications and apply for foreign Letters Patent on said inventions; and I request the Commissioner for Patents of the United States Patent and Trademark Office and the authorized official in each respective foreign patent office to issue any Letters Patent granted upon the inventions set forth in the Application(s) to Assignee; and I will execute all papers necessary in connection with the United States, international, and foreign applications when called upon to do so by Assignee.

I, the above-named, hereby covenant that no assignment, sale, agreement, or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Executed at Walthra (city/town), Massachusetts, this 22 day of February, 2019.

Michael J. Sershen

ASSIGNMENT

Whereas, I, Adam F. Bertuch, residing in South Hamilton, Massachusetts, have invented one or more new and useful inventions and have filed therefor United States Design Patent Application Serial No. 29/680,874, filed on February 20, 2019, entitled "Transportable Semiconductor Wafer Rack" (hereinafter, "Application(s)");

And whereas, And whereas, Veeco Instruments Inc., a Delaware corporation, having a place of business at 1 Terminal Drive, Plainview, New York 11803 (hereinafter called Assignee), desires to acquire the entire right, title and interest in the Application(s) and all inventions disclosed therein, and to any United States and foreign patents to be obtained therefor, and to any United States, international, and foreign patent applications to be filed thereon;

Now therefore, for good and valuable consideration, receipt whereof is hereby acknowledged, I, the above-named inventor hereby sell, assign, and transfer to Assignee, its successors and assigns, and confirm any previous assignments made by me for, the entire right, title and interest in the Application(s) and inventions therein disclosed for the United States and foreign countries, including all provisional applications relating thereto, all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents which may have been granted or may be granted hereafter thereon, and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon, and all rights of priority resulting from any of the foregoing.

And I hereby agree that Assignee may file one or more international applications and apply for foreign Letters Patent on said inventions; and I request the Commissioner for Patents of the United States Patent and Trademark Office and the authorized official in each respective foreign patent office to issue any Letters Patent granted upon the inventions set forth in the Application(s) to Assignee; and I will execute all papers necessary in connection with the United States, international, and foreign applications when called upon to do so by Assignee.

I, the above-named, hereby covenant that no assignment, sale, agreement, or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Executed at ______ (city/town), Massachusetts, this _____ day of February, 2019.

Adam F. Bertuch

ASSIGNMENT

Whereas, I, **Laurent Lecordier**, residing in Arlington, Massachusetts, have invented one or more new and useful inventions and have filed therefor United States Design Patent Application Serial No. 29/680,874, filed on February 20, 2019, entitled "Transportable Semiconductor Wafer Rack" (hereinafter, "Application(s)");

And whereas, And whereas, Veeco Instruments Inc., a Delaware corporation, having a place of business at 1 Terminal Drive, Plainview, New York 11803 (hereinafter called Assignee), desires to acquire the entire right, title and interest in the Application(s) and all inventions disclosed therein, and to any United States and foreign patents to be obtained therefor, and to any United States, international, and foreign patent applications to be filed thereon;

Now therefore, for good and valuable consideration, receipt whereof is hereby acknowledged, I, the above-named inventor hereby sell, assign, and transfer to Assignee, its successors and assigns, and confirm any previous assignments made by me for, the entire right, title and interest in the Application(s) and inventions therein disclosed for the United States and foreign countries, including all provisional applications relating thereto, all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents which may have been granted or may be granted hereafter thereon, and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon, and all rights of priority resulting from any of the foregoing.

And I hereby agree that Assignee may file one or more international applications and apply for foreign Letters Patent on said inventions; and I request the Commissioner for Patents of the United States Patent and Trademark Office and the authorized official in each respective foreign patent office to issue any Letters Patent granted upon the inventions set forth in the Application(s) to Assignee; and I will execute all papers necessary in connection with the United States, international, and foreign applications when called upon to do so by Assignee.

I, the above-named, hereby covenant that no assignment, sale, agreement, or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Executed at Arlington (city/town), Massachusetts, this 28th day of February, 2019.

Laurent Lecordier